## Notice of References Cited Application/Control No. | Applicant(s)/Patent Under Reexamination | SHUE ET AL. | Examiner | Art Unit | Page 1 of 1

## **U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-6,472,231 B1	10-2002	Gabriel et al.	438/9
	В	US-6,387,805 B2	05-2002	Ding et al.	438/687
	С	US-6,693,356 B2	02-2004	Jiang et al.	257/767
	D	US-			
	Е	US-			
	F	US-			
	G	US-			,
	Н	US-			
	1	US-			
	J	US-			
	к	US-			
	L	US-			
	М	US-			

## **FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N			_		
	0					
	Р			•		
	Ø					
	R					
	S					
	Т					

## **NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)					
	U	Adams et al. "Titanium-nitride self encapsulation of Cu and Ag films on silicon dioxide" (1997) Thin Solid Films pp. 448-454					
	٧						
	w						
	х						

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.